



SOT1261-1

plastic, thermal enhanced super thin quad flat package; no leads; 12 terminals; body 2.0 x 2.0 x 0.3 mm

28 June 2016

Package information

1. Package summary

Dimensions (mm)	2.0 x 2.0 x 0.3
Terminal position code	Q (quad)
Package type descriptive code	SOT1261
Package outline version code	SOT1261-1
Manufacturer package code	SOT1261
Package type industry code	HX2QFN12
Package outline version description	plastic, thermal enhanced super thin quad flat package; no leads; 12 terminals; body 2.0 x 2.0 x 0.3 mm
Package style descriptive code	HXQFN (thermal enhanced extremely thin quad flatpack; no leads)
Package body material type	P
Mounting method type	S (surface mount)
Security status	COMPANY PUBLIC
Issue date	20-6-2014

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
A	seated height		0.28	-	0.3	0.33	mm
D	package length		1.95	-	2	2.05	mm
E	package width		1.95	-	2	2.05	mm
e	nominal pitch		-	-	0.5	-	mm
n ₂	actual quantity of termination		-	-	12	-	



2. Package outline

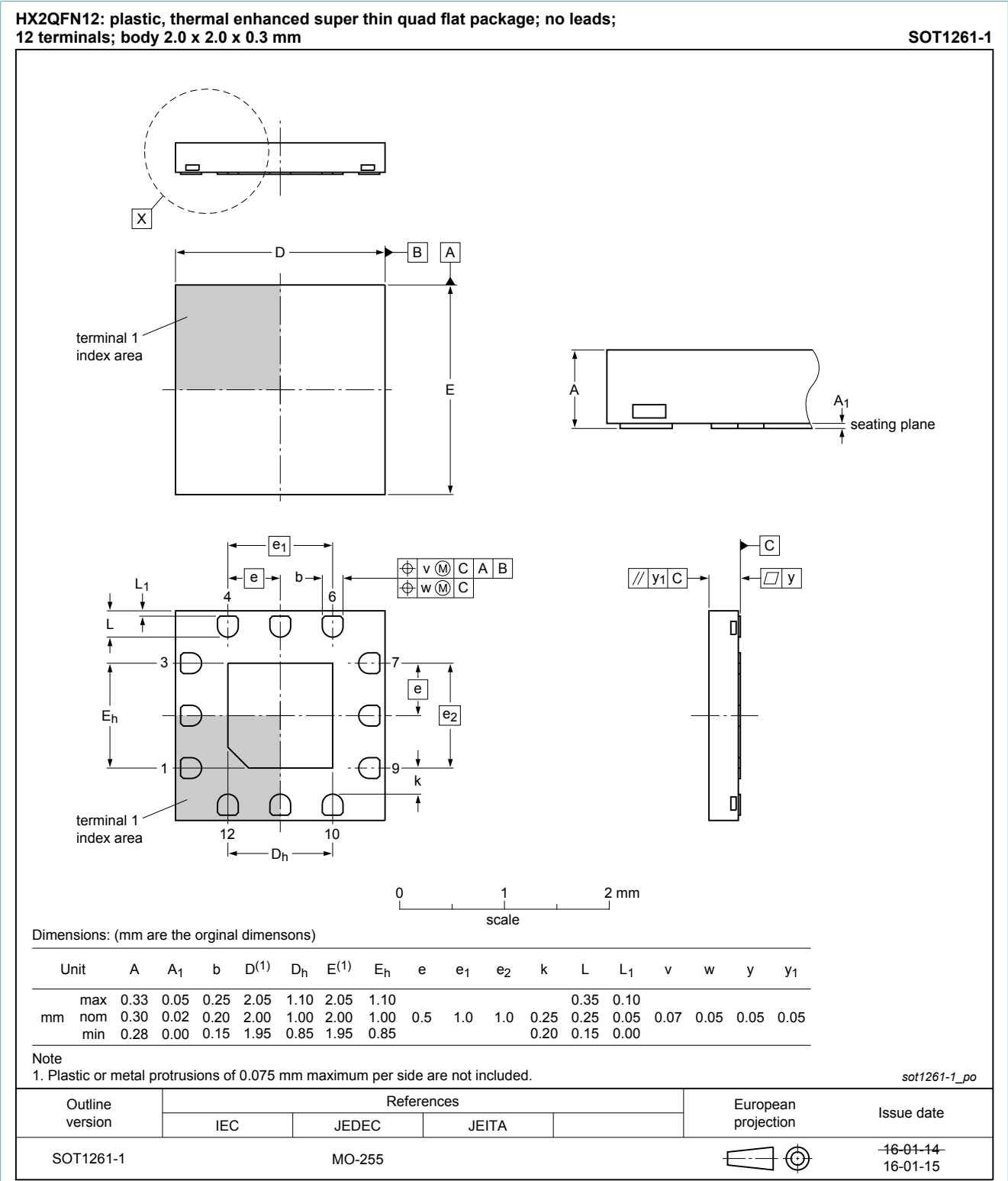


Fig. 1. Package outline HX2QFN12 (SOT1261-1)

plastic, thermal enhanced super thin quad flat package; no leads; 12 terminals; body 2.0 x 2.0 x 0.3 mm

3. Soldering

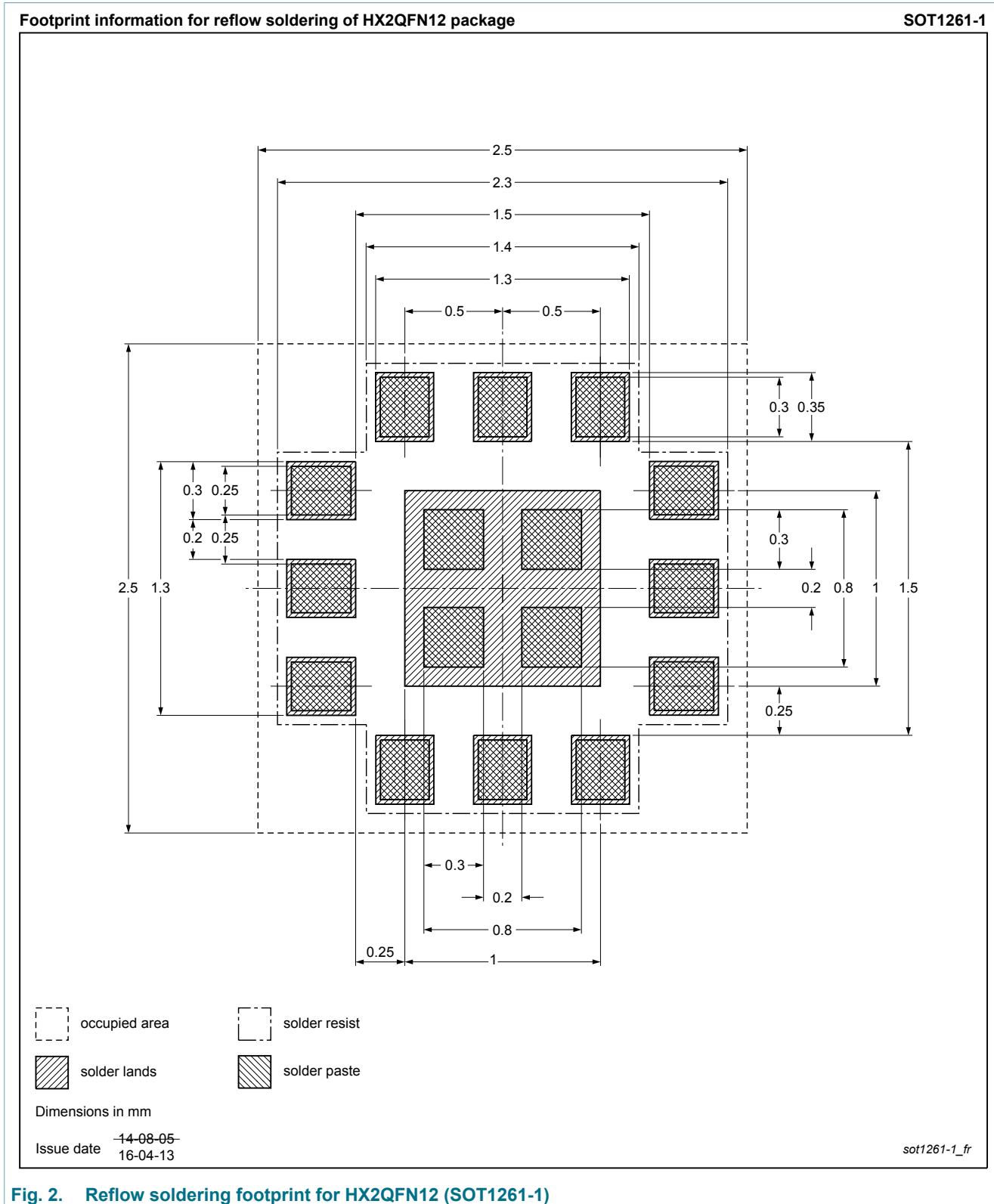


Fig. 2. Reflow soldering footprint for HX2QFN12 (SOT1261-1)

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4. Legal information

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